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Example:xLED-SEO-60 Height (mm) Anodising Color B-Black C-Clear Z-Custom

Ex.order code - 12

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.

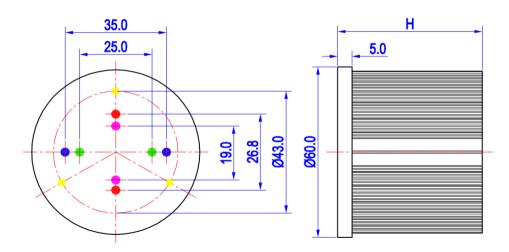
- MingfaTech reserves the right to change products or specifications without prior notice.

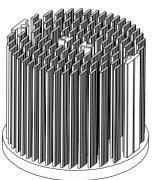
means option 1 and 2 combined

details Combinations available

Mounting Options - see graphics for

LEDiL products MOUNTING THREAD THREAD HOLE THREAD Holder NO. Module type OPTION DEPTH DISTANCE Olivia series Ronda series 19.0mm/ 2-@180° МЗ 6 5mm 1 FN15972-xxx; BJB Holder COB Size FN14637-S; FN15971-xxx; 47.319.2021.50 25.0mm/ 2-@180° 13.5×13.5mm 2 МЗ 6.5mm FN15969-xxx; AAG.STUCCHI (Zhaga book 11) 8101-G2 3 26.8mm/ 2-@180° 1 МЗ 6.5mm BJB Holder COB Size FN14637-S; FN15xxx-xx: 47.319.2021.50 35.0mm/ 2-@180° 19×19mm FN14828-M; 4 M3 6.5mm AAG.STUCCHI (Zhaga book 3) 8101-G2 5 AC Module / / / M2 6.5mm 43.0mm/ 3-@120°





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XLED

xLED-SEO-6030 Pin Fin Heat Sink Φ60mm for Seoul

The product deta table

RLED	Model No.	xLED-SEO-6030
	Heatsink Size	Ф60хH30mm
	Heatsink Material	AL1070
	Finish	Black Anodized
	Weight (g)	80.0
	Dissipated power (Ths-amb,50°C)	10.0 (W)
	Cooling surface area (mm ²)	40973
	Thermal Resistance (Rhs-amb)	5.0 (°C/W)

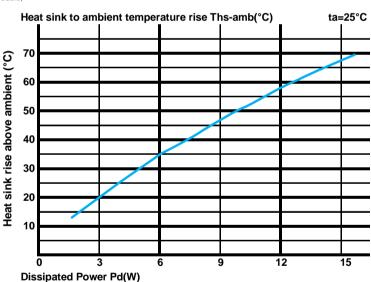
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

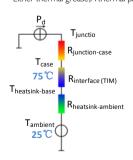
*To calculate the dissipated power please use the following formula: $Pd = Pe \times (I - \eta L)$.

Pd - Dissipated power ; Pe - Electrical power ; $\eta L = \mbox{Light effciency of the LED module;}$

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-SEO-6030	
Dissipated Power Pd(W)	3.0	6.67	20.0
	6.0	5.67	34.0
	9.0	5.11	46.0
	12.0	4.83	58.0
	15.0	3.80	57.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material). MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta)/Pd$

 $\theta\,$ - Thermal Resistance [°C/W] ; $\,$ Ths - Heatsink temperature ; $\,$ Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [°C/W], the thermal resistance with the heat sink is $R_{\text{heatsink-ambert}}$ [°C/W], and the ambient temperature is T_{ambert} [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction}=(R_{junction-case}+R_{case-ambient})$ Pd+ $T_{ambient}$

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